



Dual N-Channel PowerTrench MOSFET

General Description

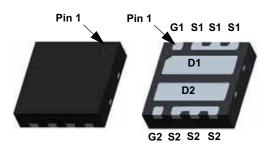
This device includes two 40V N-Channel MOSFETs in a dual **DFN3X3** (3 mm X 3 mm MLP) package. The package is enhanced for exceptional thermal performance.

Features

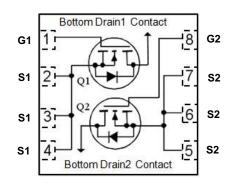
- Max $r_{DS(on)}$ = 20 m Ω at V_{GS} = 10 V, I_D = 7 A
- Max $r_{DS(on)}$ = 27 m Ω at V_{GS} = 4.5 V, I_D = 6 A
- Low Inductance Packaging Shortens Rise/Fall Times
- Lower Switching Losses
- 100% Rg Tested
- Termination is Lead-free and RoHS Compliant

Applications

- Battery Protection
- Load Switching
- Point of Load







Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
7N40	RMD7N40DN	DFN3X3	13 "	12 mm	3000 units

Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parame	eter		Ratings	Units
V _{DS}	Drain to Source Voltage			40	V
V _{GS}	Gate to Source Voltage			±20	V
I _D	Drain Current -Continuous	T _C = 25 °C		20	
	-Continuous	T _A = 25 °C	(Note 1a)	7	Α
	-Pulsed		(Note 4)	50	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	13	mJ
D	Power Dissipation	T _C = 25 °C		12	w
PD	Power Dissipation $T_A = 25 \text{ °C}$ (Note 1a)			1.9	V
T _J , T _{STG}	Operating and Storage Junction Tempera		-55 to +150	°C	

Thermal Characteristics

R _{0JC}	Thermal Resistance, Junction to Case	9.7	°C/M
$R_{ ext{ heta}JA}$	Thermal Resistance, Junction to Ambient (Note 1a) 65	°C/W

Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units

Off Characteristics

BV _{DSS}	Drain to Source Breakdown Voltage	I _D = 250 μA, V _{GS} = 0 V	40			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		23		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 32 V, V _{GS} = 0 V			1	μA
I _{GSS}	Gate to Source Leakage Current, Forward	V _{GS} = ±20 V, V _{DS} = 0 V			100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \ \mu A$	1.0	1.8	3.0	V
$\Delta V_{GS(th)} \Delta T_J$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 µA, referenced to 25 °C		-5		mV/°C
		V _{GS} = 10 V, I _D = 7 A		16	20	
r	Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 6 \text{ A}$		21	27	mΩ
r _{DS(on)} Static Drain to Source On Resistant		V _{GS} = 10 V, I _D = 7 A T _J = 125 °C		23	29	- 11152
9 _{FS}	Forward Transconductance	V _{DD} = 5 V, I _D = 7 A		27		S

Dynamic Characteristics

C _{iss}	Input Capacitance	<u> </u>		513	720	pF
C _{oss}	Output Capacitance	V _{DS} = 20 V, V _{GS} = 0 V f = 1MHz		137	195	pF
C _{rss}	Reverse Transfer Capacitance	1 = 110112		9.3	15	pF
Rg	Gate Resistance		0.1	2.6	3.6	Ω

Switching Characteristics

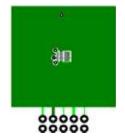
t _{d(on)}	Turn-On Delay Time		5.5	11	ns
t _r	Rise Time	V_{DD} = 20 V, I _D = 7 A V _{GS} = 10 V, R _{GEN} = 6 Ω	1.2	10	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 10 V, R _{GEN} = 6 Ω	13	24	ns
t _f	Fall Time		1.3	10	ns
~	Total Gate Charge	V _{GS} = 0 V to 10 V	7.6	11	nC
Q _{g(TOT)}	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V} \text{ V}_{DD} = 20 \text{ V}$	3.6	5.1	nC
Q _{gs}	Gate to Source Charge	I _D = 7 A	1.5		nC
Q _{gd}	Gate to Drain "Miller" Charge		1.0		nC

Drain-Source Diode Characteristics

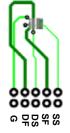
V _{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _S = 7 A (Note 2)	0.85	1.3	V
		$V_{GS} = 0 V, I_S = 1.4 A$ (Note 2)	0.75	1.2	v
t _{rr}	Reverse Recovery Time	I _F = 7 A, di/dt = 100 A/μs	16	29	ns
Q _{rr}	Reverse Recovery Charge	$r_F = 7 A$, divat = 100 A/µs	3.9	10	nC

NOTES:

1. R_{0JA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0JC} is guaranteed by design while R_{0CA} is determined by the user's board design.



a. 65 °C/W when mounted on a 1 in² pad of 2 oz copper



b. 155 °C/W when mounted on a minimum pad of 2 oz copper

2. Pulse Test: Pulse Width < $300 \ \mu$ s, Duty cycle < 2.0 %. 3. E_{AS} of 13 mJ is based on starting T_J = 25 °C, L = 3 mH, I_{AS} = 3 A, V_{DD} = 40 V, V_{GS} = 10 V. 100% tested at L = 0.1 mH, I_{AS} = 11 A. 4. Pulse Id refers to Figure.11 Forward Bias Safe Operation Area.

RATING AND CHARACTERISTICS CURVES (RMD7N40DN)

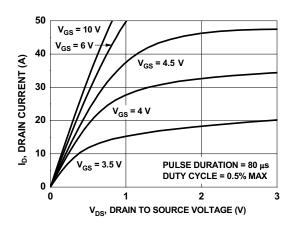
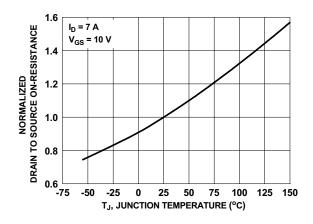
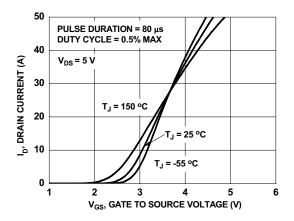
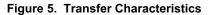


Figure 1. On-Region Characteristics









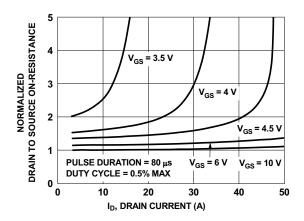


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

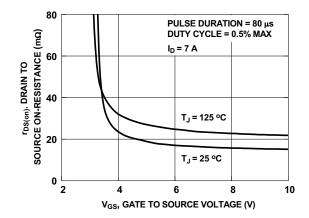


Figure 4. On-Resistance vs Gate to Source Voltage

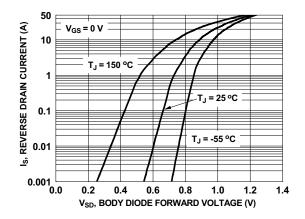
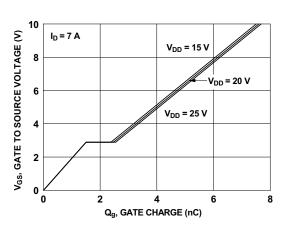


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

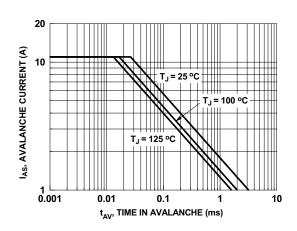




RATING AND CHARACTERISTICS CURVES (RMD7N40DN)

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Figure 7. Gate Charge Characteristics





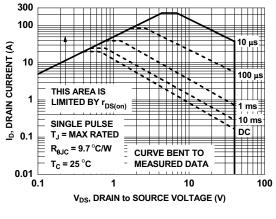


Figure 11. Forward Bias Safe Operating Area

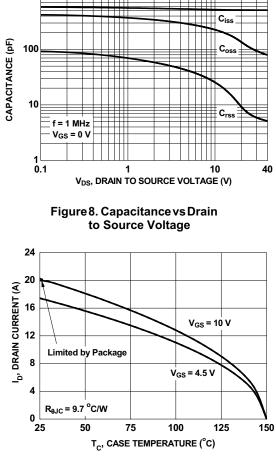


Figure 10. Maximum Continuous Drain Current vs Case Temperature

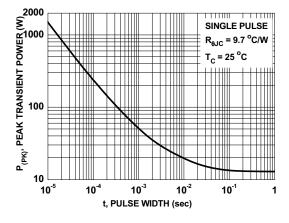
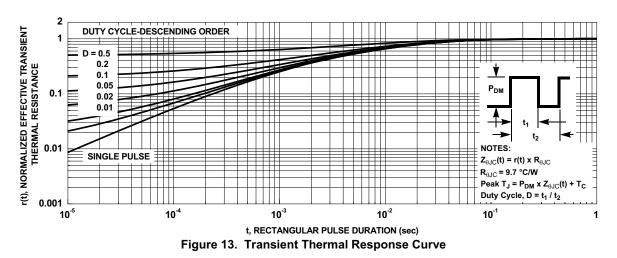


Figure 12. Single Pulse Maximum Power Dissipation

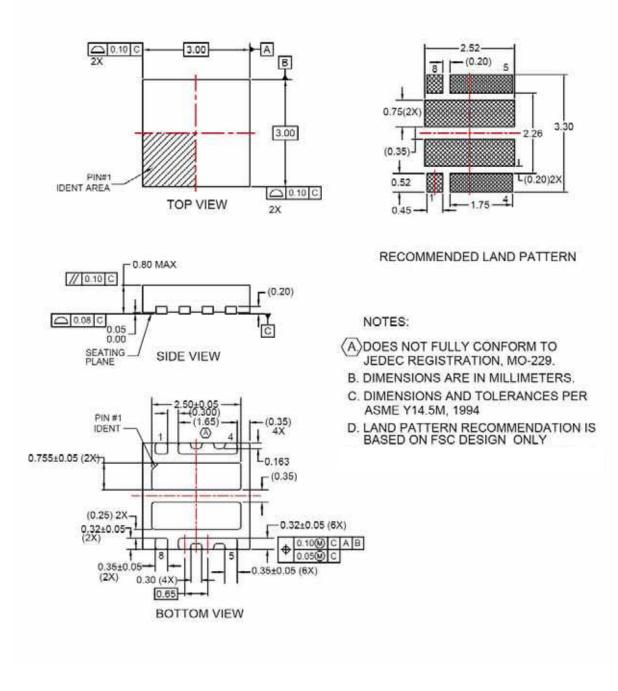




RATING AND CHARACTERISTICS CURVES (RMD7N40DN)



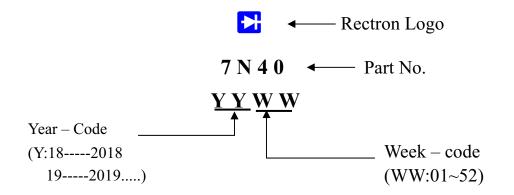
Dimensional Outline and Pad Layout







Marking on the body





Package	Tube (pcs/tube)	Tube (pcs/inner box)	Tube (pcs/cartoon)	Tape&Reel (pcs/reel)	Tape&Reel (pcs/inner box)	Tape&Reel (pcs/cartoon)
DFN	100	10,000	100,000	2,500	5,000	40,000
SOP-8	100	10,000	100,000	4,000	4,000	20,000
TSSOP-8	100	32,000	128,000	3,000	6,000	48,000
SOT-23-3L				3,000	30,000	120,000
SOT-23-6L				3,000	30,000	120,000
SOT-23(6R)				3,000	30,000	120,000
SOT-363				3,000	30,000	120,000
SOT-523				3,000	30,000	120,000
SOT223				2,500	2,500	20,000
TO-220	50	1,000	5,000			
TO-220F	50	1,000	10,000			
TO-247	30	300	1,200			
TO-251	80	4,000	40,000			
TO-251S(4R)	80	4,000	40,000			
TO-252-2L(4R)	80	4,000	40,000	2,500	2,500	25,000
TO-263-2L	50	1,000	10,000	800	800	8,000
TO-3P	30	300	3,000			
TO-92				1,000(袋装)	10,000	100,000



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